

Material Content Data Sheet

Sales Product Name	AIM12S54EB1	**Issued**	09. July 2025
MA#	MA006155039		
Package	PG-MDIP-24-64	**Weight:**	7150.60 mg

Construction Element	Material group	Materials	CAS if applicable	Weight [mg]	Average mass [%]	Sum [%]	Average mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	7.056	0.10	0.10	987	987
chip_2	inorganic material	siliconcarbide	409-21-2	2.212	0.03	0.03	309	309
chip_3	inorganic material	siliconcarbide	409-21-2	2.212	0.03	0.03	309	309
chip_4	inorganic material	siliconcarbide	409-21-2	2.212	0.03	0.03	309	309
chip_5	inorganic material	siliconcarbide	409-21-2	2.212	0.03	0.03	309	309
chip_6	inorganic material	siliconcarbide	409-21-2	2.212	0.03	0.03	309	309
chip_7	inorganic material	siliconcarbide	409-21-2	2.212	0.03	0.03	309	309
leadframe	inorganic material	phosphorus	7723-14-0	0.383	0.01		54	
	non noble metal	iron	7439-89-6	1.276	0.02		178	
	non noble metal	copper	7440-50-8	1274.200	17.82	17.85	178195	178427
wire	noble metal	gold	7440-57-5	0.609	0.01		85	
	non noble metal	aluminium	7429-90-5	51.204	0.72	0.73	7161	7246
encapsulation	organic material	carbon black	1333-86-4	30.428	0.43		4255	
	plastics	epoxy resin	-	380.356	5.32		53192	
	inorganic material	silicondioxide	60676-86-0	3392.775	47.45	53.20	474476	531923
leadfinish	non noble metal	tin	7440-31-5	41.241	0.58	0.58	5767	5767
plating	non noble metal	nickel	7440-02-0	5.991	0.08	0.08	838	838
solder	non noble metal	antimony	7440-36-0	0.327			46	
	noble metal	silver	7440-22-4	0.817	0.01		114	
	non noble metal	tin	7440-31-5	2.125	0.03	0.04	297	457
glue	organic material	ethene, 1,1,2,2-tetrafluoro-	925918-64-5	0.006			1	
	inorganic material	silicondioxide	60676-86-0	0.218			30	
	plastics	acrylic resin	-	0.256			36	
	plastics	maleimide resin	-	0.257			36	
	plastics	epoxy resin	-	0.322			45	
	noble metal	silver	7440-22-4	0.770	0.01	0.01	108	256
smd	inorganic material	silicondioxide	60676-86-0	0.002			1	
	noble metal	gold	7440-57-5	0.008			1	
	noble metal	palladium	7440-05-3	0.013			2	
	organic material	ethyl cellulose	9004-57-3	0.016			2	
	noble metal	silver	7440-22-4	0.021			3	
	organic material	DEGBE	112-34-5	0.071			10	
	inorganic material	cobalt(II)oxide	1307-96-6	0.136			19	

	inorganic material	copperoxide	1317-38-0	0.390	0.01		55	
	inorganic material	manganesedioxide	1313-13-9	0.446	0.01	0.02	62	155
pcb metal	non noble metal	copper	7440-50-8	13.571	0.19	0.19	1898	1898
pcb plastic	miscellaneous	miscellaneous	-	26.373	0.37		3688	
	inorganic material	silicondioxide	60676-86-0	42.196	0.59		5901	
	organic material	Poly[phenylglycidylether-coformaldehyde]	28064-14-4	50.108	0.70		7008	
	inorganic material	glass fibre	-	145.050	2.03	3.69	20285	36882
pcb plating	noble metal	gold	7440-57-5	0.042			6	
	non noble metal	nickel	7440-02-0	1.898	0.03	0.03	265	271
dcb ceramic	inorganic material	zirconium dioxide	1314-23-4	5.122	0.07		716	
	inorganic material	aluminum nitride	24304-00-5	454.293	6.35	6.42	63532	64248
dcb metal	non noble metal	copper	7440-50-8	1206.956	16.88	16.88	168791	168791
deviation	< 10%				Sum in total:	100.00		1000000

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com